

**AMENDMENTS TO THE SPECIFICATION:**

Please replace paragraph [0003] with the following amended paragraph:

These basic forms are suitable for most applications of a transition. However, there remain applications where the basic forms are not used due to space constraints and performance requirements. For example, in a phased array having multiple waveguide ports, the available space limits the dimensions of the microstrip-waveguide transition. In addition, some applications require a hermetic seal between the microstrip and the waveguide. ~~Current microstrip-waveguide transitions can be labor intensive to construct due, for example, to alignment needs of numerous parts in the current microstrip-waveguide transitions.~~ For larger millimeter wave phased array systems (e.g., those having thousands of waveguide ports), the labor cost can become impractical. Even with modern automated assembly equipment, the construction time is affected by need for alignment in the interconnect systems used today.

Please replace paragraph [0007] with the following amended paragraph:

[0007] Exemplary embodiments are also directed to a microstrip-waveguide transition including a waveguide having an open end, a dielectric substrate having a first side surface attached to the open end, a microstrip probe on a second side surface of the dielectric substrate, a backshort cap attached to the second side surface, and wherein corners of the waveguide, ~~dielectric substrate~~ and backshort cap are in alignment. As shown in Fig. 3, a dielectric substrate can be held within the microstrip-waveguide transition, the backshort cap being in alignment with the waveguide.